



## Customer Information Notification

202102020I : Standardization Packing Method for (H)LQFP in Reels

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Mar 18, 2021 **Effective date:** Jun 10, 2021

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### Management summary

Standardization of the packing method for reels with package types TQFP64 and (H)LQFP144. The current packing method for products listed is one PQ box in an outer box with cushions. The new packing method will be single PQ box with foam buffer integrated at the individual Pack Unit level.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

NXP will standardize the packing method for reels with package types TQFP64 and (H)LQFP144.

The current packing method for products listed is one PQ box in an outer box with cushions. The new packing method will be single PQ box with foam buffer.

The single PQ box with foam buffer pass the 1 meter drop-test for the package variants. See details in attached presentation.

The new packing method will be introduced in February 2021. Existing inventory will be shipped until depleted.

### Reason

To inform the customer about the new packing method for reels for the products in TQFP64 and (H)LQFP144. The new packing method for reels will have less waste of packing material (environmental), reduced shipment volume and more efficient handling times at customer site.

### Identification of Affected Products

Product identification does not change

## **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality

### **Data Sheet Revision**

No impact to existing datasheet

### **Disposition of Old Products**

Existing inventory will be shipped until depleted

## **Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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### **Affected OPN**

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PCF8578HT/1,518

PCF85176H/1,518

PCA85176H/Q900/1,5